



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



For Infrared Ray LED Module	<h1>AAM11</h1>
MID Package	



Individual piece
(cut shape)

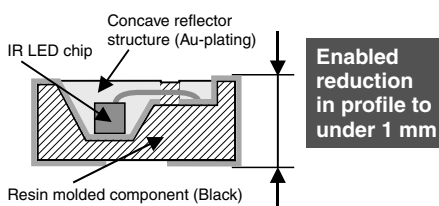
RoHS compliant

FEATURES

1. Realization of small, low-profile reflector package through application of our unique MID* technology (MIPTEC).

Individual piece: 2.3 × 1.95 × 0.9 mm

<Cross section of package>

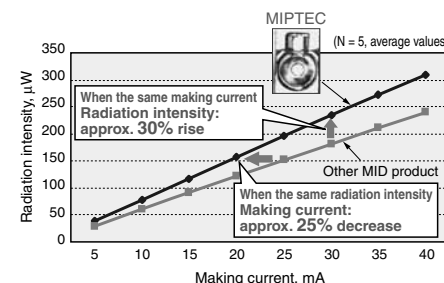


Note: LED chip to be prepared and mounted separately by the customer.

* MID (Molded Interconnect Devices): Molded components with an electrical circuit formed on 3D surfaces.

2. A concave reflector structure with good directivity and increased light extraction efficiency due to bright plating specifications contributes to decreased module power consumption

* The graph below uses typical values, and details will vary according to the LED chip specifications.



APPLICATIONS

- Light projection type Inductive proximity sensor package
 - Smartphone display control
 - Finder control of single-lens reflex
- IR LED lighting for surveillance camera

ORDERING INFORMATION

AAM 1 1 0 1 0 6 2

Molding material/Size of sheet
1: PPA (Black)
50 × 70 mm

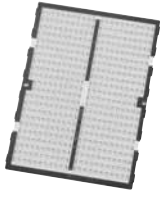

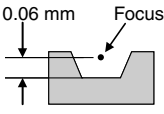
Unit size (2 digits)
01: 2.3 × 1.95 × 0.9 mm

Focal length (2 digits)
06: 0.06 mm*

Au-plating thickness
2: 0.2±0.1 µm

* For requests of products with different focal lengths, please contact our sales office.

PRODUCT TYPES

Appearance of sheet	Material of molding sheet	Appearance of individual piece	Focal length	Au-plating thickness (μm)	Part number (Delivered in sheet form)	Packing (one carton)
 50 × 70 mm	Polyphthalamide (PPA) Black	 2.3 × 1.95 mm h = 0.9 mm (436 pieces/sheet)	 0.06 mm Focus Distance from the bottom surface of the mounted LED chip to the focal section	0.2±0.1	AAM1101062	6 trays (Contains 432 sheets)

Notes: 1. This product is delivered in sheet form, and customers are required to mount the LED chips and cut the sheet into individual pieces.
 2. For requests of focal lengths other than those mentioned above, please contact our sales office.
 3. For requests of evaluation samples, please contact our sales office.

SPECIFICATIONS

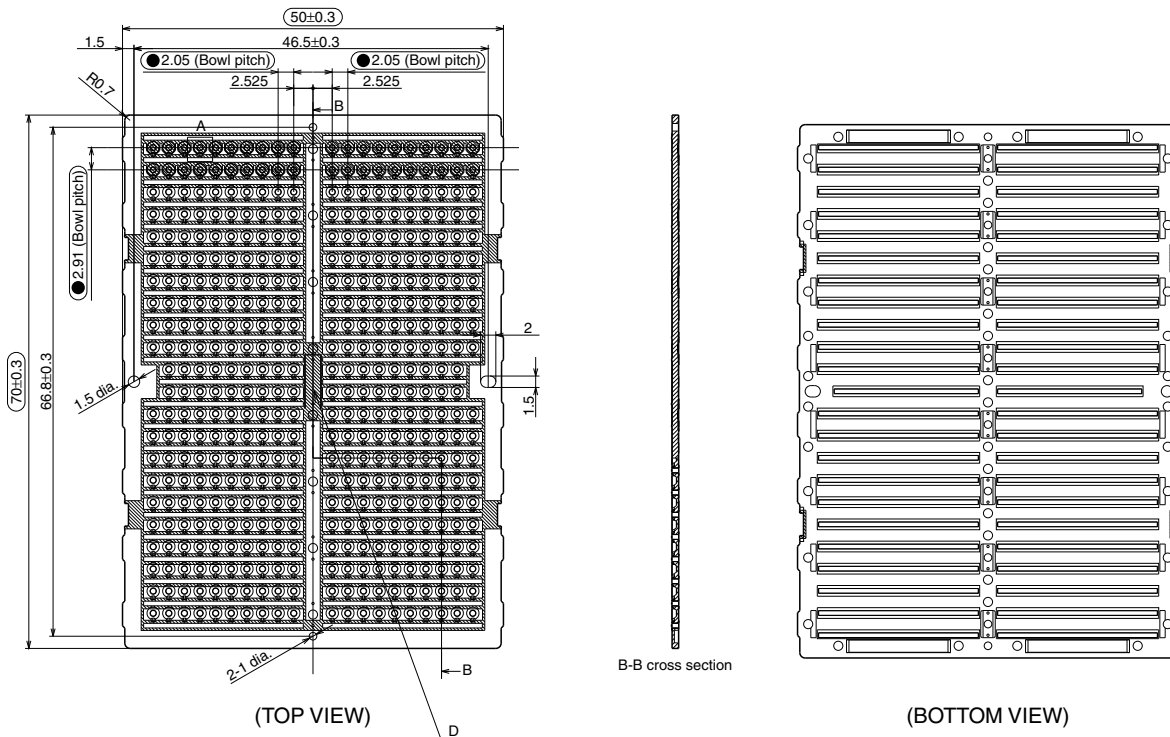
Product specifications

Item	Specifications	
Plating thickness*	Cu-plating	13±7 μm
	Ni-plating	6±4 μm
	Au-plating	0.2±0.1 μm (AAM1101062)
Plating adhesion strength*	0.39 N/m or higher (initial)	
Ambient environment (No icing and condensation at low temperatures)	Temperature	-20°C to 50°C Maximum temperature when applying an electrical current: 85°C
	Humidity	15% to 85%RH
	Pressure	86 kPa to 106 kPa

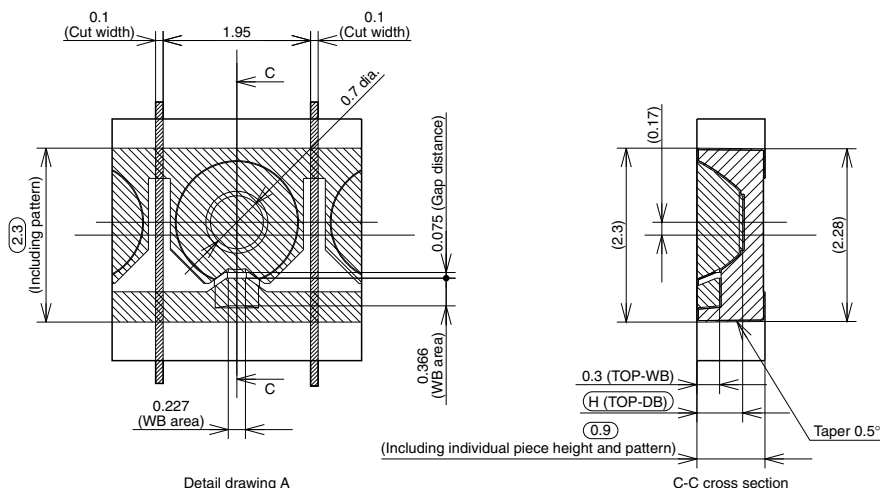
*Measured at point of D (see "Sheet dimensions")

DIMENSIONS (Unit: mm)

1. Sheet dimensions (Delivered form)



2. Individual piece (cut shape)



General tolerance: ±0.1

NOTES

1. Handling during storage

1) Although the outermost surface is coated in Au-plating, if exposed to atmospheres containing corrosive gases, humidity or at high temperature, the underlying nickel or copper may corrode causing discoloration of the plated surface, decreasing reflectance, and this may lead to decreased mountability or joint reliability of LED components or soldering. Therefore, please pay close attention to the atmosphere used for storage.

2) Storage conditions ("After opening" refers to after opening the packing bag)

The following conditions must be followed in order to maintain plating adhesive strength and external performance.

	Before opening	After opening
Temperature	15°C to 35°C	23°C±3°C
Humidity	RH25% to 75%	RH50% or less
Pressure	86 kPa to 106 kPa	86 kPa to 106 kPa
Storage life (*2)	3 months	1 month (*1)

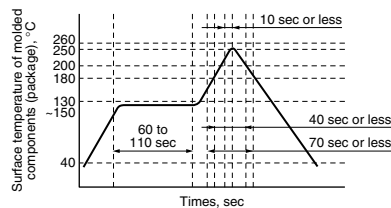
*1: Please keep it in desiccator set into the clean room.

*2: The storage life means the length from the date (lot number) printed on packaging.

2. Soldering

Please use the reflow temperature profile conditions recommended below for reflow soldering. Please contact us before using a temperature profile other than that described below.

Recommended soldering temperature conditions



Please refer to the latest product specifications when designing your product.

Please contact

Panasonic Corporation

Electromechanical Control Business Division

■ 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8506, Japan
industrial.panasonic.com/ac/e/

Panasonic[®]

©Panasonic Corporation 2016